



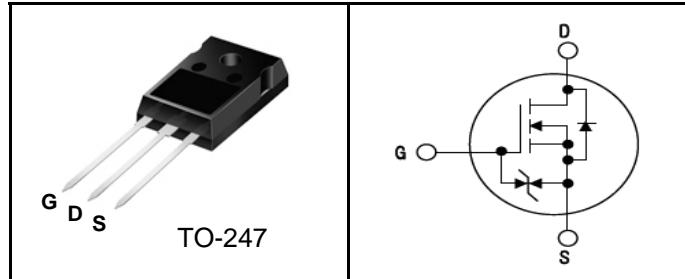
达善微科技

MPSW60M190B

## 600V N-Channel Super Junction MOSFET

### Features

- $BV_{DSS}=600V$ ,  $I_D=17.6A$
- $R_{DS(on)}:0.19\Omega$  (Max) @  $V_{GS}=10V$
- Very Low FOM ( $R_{DS(on)} \times Q_g$ )
- Extremely low switching loss
- Excellent stability and uniformity
- 100% Avalanche Tested
- Built-in ESD Diode



### Application

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)
- AC to DC Converters
- Telecom, Solar

RoHS

### Device Marking and Package Information

Ordering code	Package	Marking
MPSW60M190B	TO-247	MP60M190B

### Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise specified

Symbol	Parameter	Value	Unit
$V_{DSS}$	Drain-Source Voltage	600	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current - Continuous ( $T_c = 25^\circ C$ )	17.6	A
	Drain Current - Continuous ( $T_c = 100^\circ C$ )	11.2	A
$I_{DM}^{(1)}$	Drain Current - Pulsed	53	A
$E_{AS}^{(2)}$	Single Pulsed Avalanche Energy	262	mJ
$I_{AR}$	Avalanche Current	2.45	A
$dv/dt$	MOSFET $dv/dt$ ruggedness, $V_{DS}=0\dots 400V$	50	V/ns
$dv/dt$	Reverse diode $dv/dt$ , $V_{DS}=0\dots 400V$ , $I_{DS} \leq I_D$	15	V/ns
$P_D$	Power Dissipation ( $T_c = 25^\circ C$ )	130	W
$V_{ESD(G-S)}$	Gate source ESD(HBM-C=100pF, $R=1.5K\Omega$ )	2000	V
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +150	°C

### Thermal Resistance Characteristics

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	0.96	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient , Max.	62.5	°C/W



懋昌电源

MPSW60M190B

**Electrical Characteristics**  $T_J=25\text{ }^{\circ}\text{C}$  unless otherwise specified

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
<b>On Characteristics</b>						
$V_{GS}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$ , $I_D = 670\text{ }\mu\text{A}$	2.0	-	4.0	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS} = 10\text{ V}$ , $I_D = 6.9\text{ A}$	-	0.165	0.19	$\Omega$
<b>Off Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}$ , $I_D = 1\text{ mA}$	600	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 600\text{ V}$ , $V_{GS} = 0$	-	-	1	$\mu\text{A}$
		$V_{DS} = 600\text{ V}$ , $T_C = 150\text{ }^{\circ}\text{C}$	-	-	100	$\mu\text{A}$
$I_{GSS}$	Gate-Body Leakage Current	$V_{GS} = \pm 20\text{ V}$ , $V_{DS} = 0\text{ V}$	-	-	$\pm 1$	$\mu\text{A}$
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS} = 400\text{ V}$ , $V_{GS} = 0\text{ V}$ , $f = 1.0\text{ MHz}$	-	1750	-	pF
$C_{oss}$	Output Capacitance		-	41	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	2.4	-	pF
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-On Time	$V_{DS} = 300\text{ V}$ , $I_D = 8.7\text{ A}$ , $R_G = 25\text{ }\Omega$ (Note 3,4)	-	39	-	ns
$t_r$	Turn-On Rise Time		-	21	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	171	-	ns
$t_f$	Turn-Off Fall Time		-	18	-	ns
$Q_{g(}}$	Total Gate Charge	$V_{DS} = 480\text{ V}$ , $I_D = 8.7\text{ A}$ , $V_{GS} = 10\text{ V}$ (Note 3,4)	-	40	-	nC
$Q_{gs}$	Gate-Source Charge		-	8	-	nC
$Q_{gd}$	Gate-Drain Charge		-	12	-	nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain-Source Diode Forward Current	-	-	17.6	A	
$I_{SM}$	Maximum Pulsed Drain-Source Diode Forward Current	-	-	53	A	
$V_{SD}$	Drain-Source Diode Forward Voltage	$V_{GS} = 0\text{ V}$ , $I_S = 8.7\text{ A}$	-	-	1.3	V
$trr$	Reverse Recovery Time	$V_R = 400\text{ V}$ , $I_F = 8.7\text{ A}$ $dI_F/dt = 100\text{ A}/\mu\text{s}$	-	340	-	ns
$Qrr$	Reverse Recovery Charge		-	4.7	-	$\mu\text{C}$

**Notes :**

- Repetitive Rating : Pulse width limited by maximum junction temperature
- $I_{AS}=2.45\text{ A}$   $V_{DD}=50\text{ V}$ ,  $R_G=25\Omega$ , Starting  $T_J=25\text{ }^{\circ}\text{C}$
- Pulse Test : Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$
- Essentially Independent of Operating Temperature

## Typical Characteristics

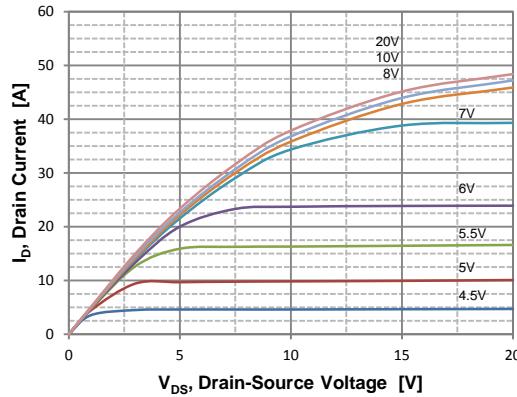


Figure 1. On Region Characteristics

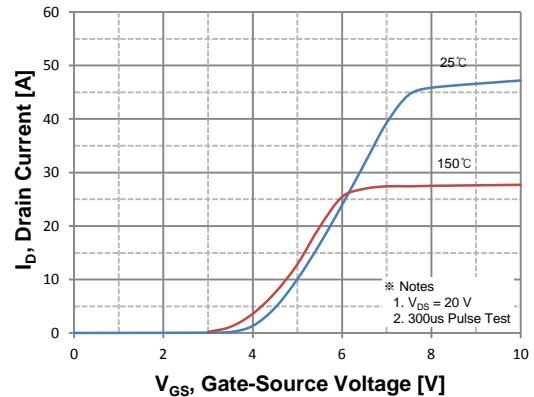


Figure 2. Transfer Characteristics

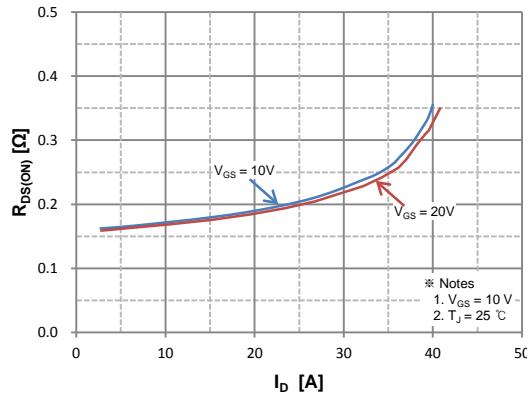


Figure 3. On Resistance Variation vs Drain Current and Gate Voltage

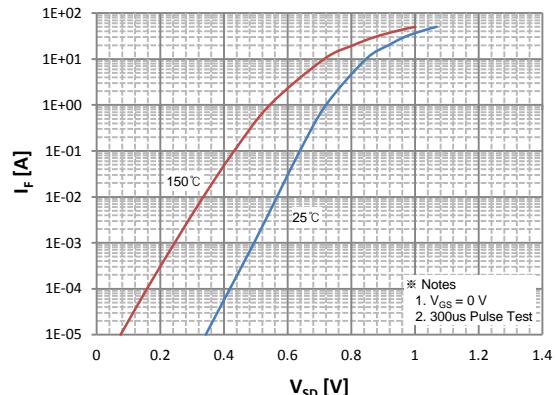


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

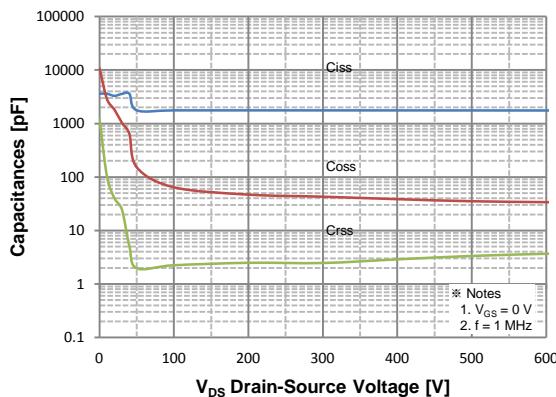


Figure 5. Capacitance Characteristics

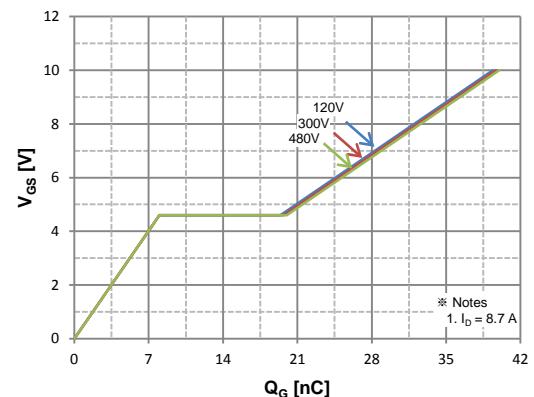
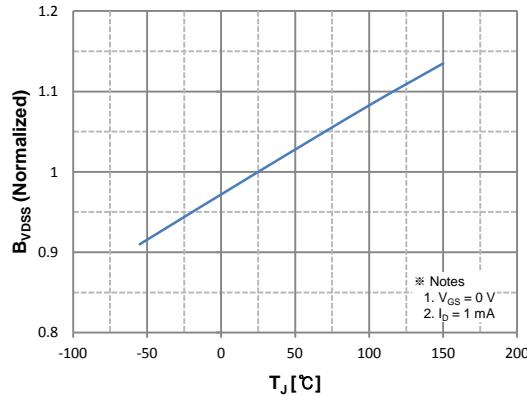
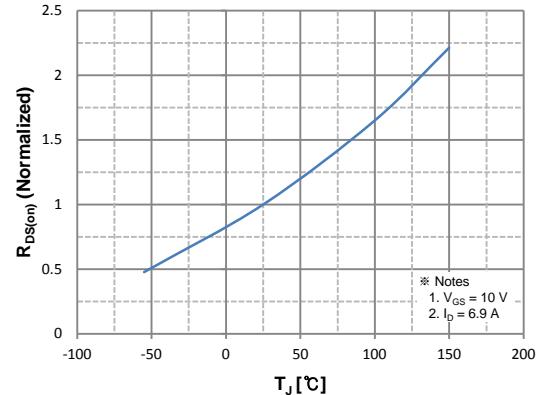


Figure 6. Gate Charge Characteristics

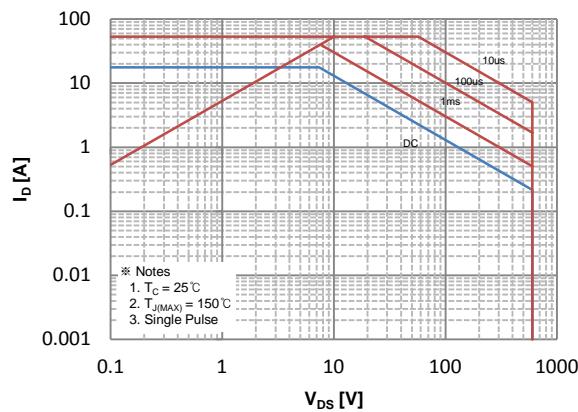
## Typical Characteristics



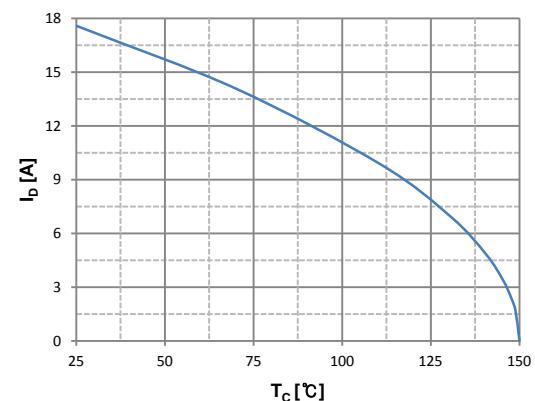
**Figure 7. Breakdown Voltage Variation  
vs. Temperature**



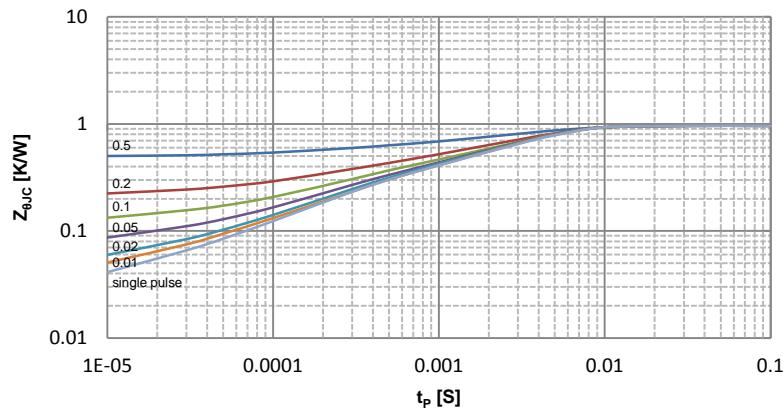
**Figure 8. On-Resistance Variation  
vs. Temperature**



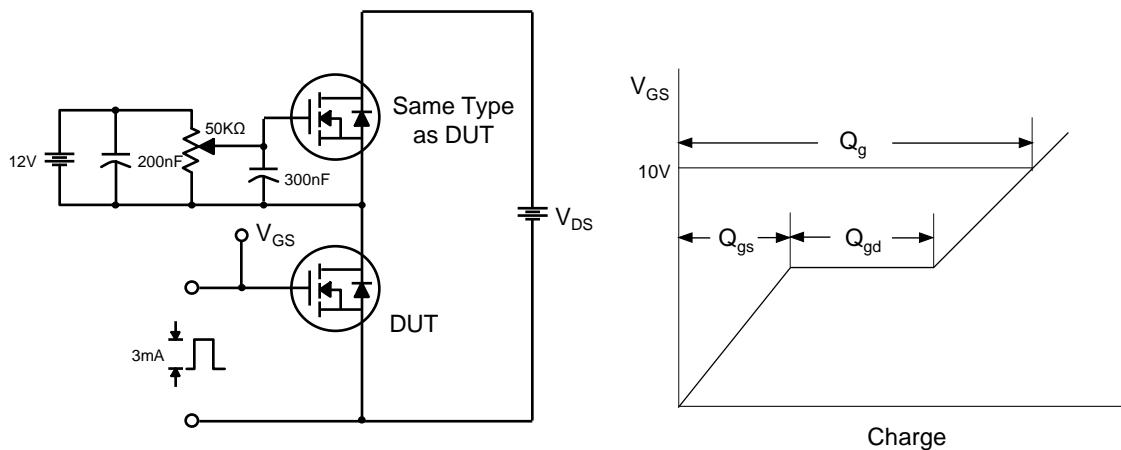
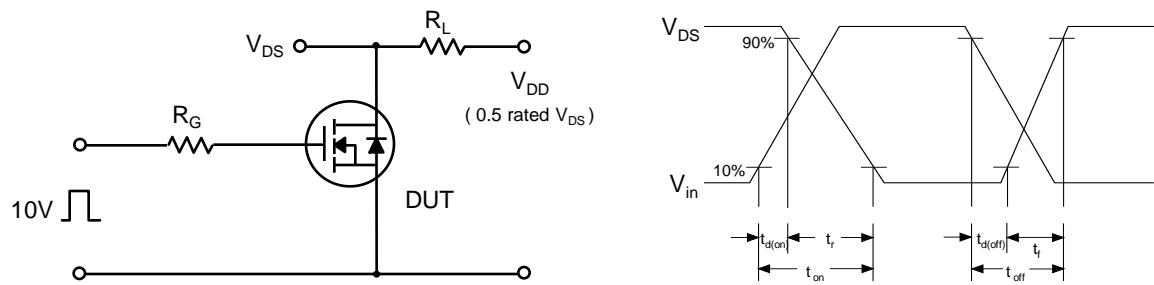
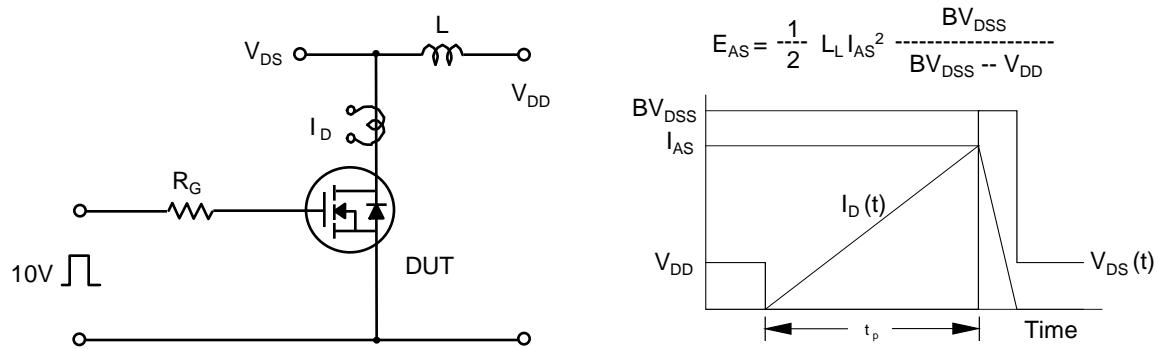
**Figure 9. Maximum Safe Operating Area**

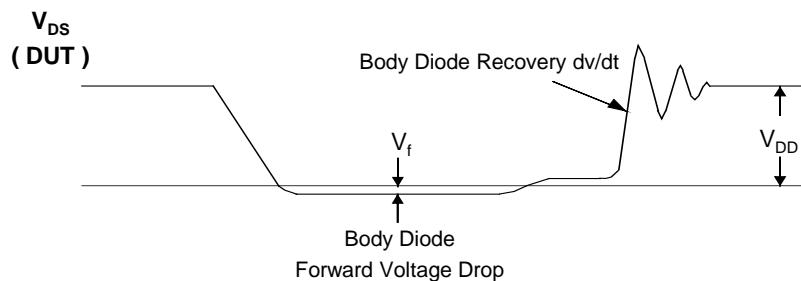
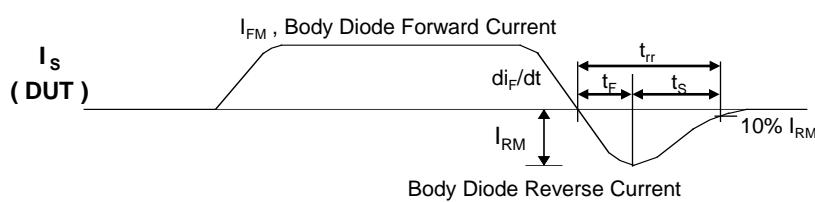
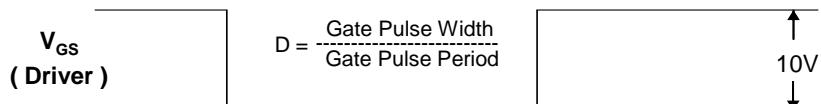
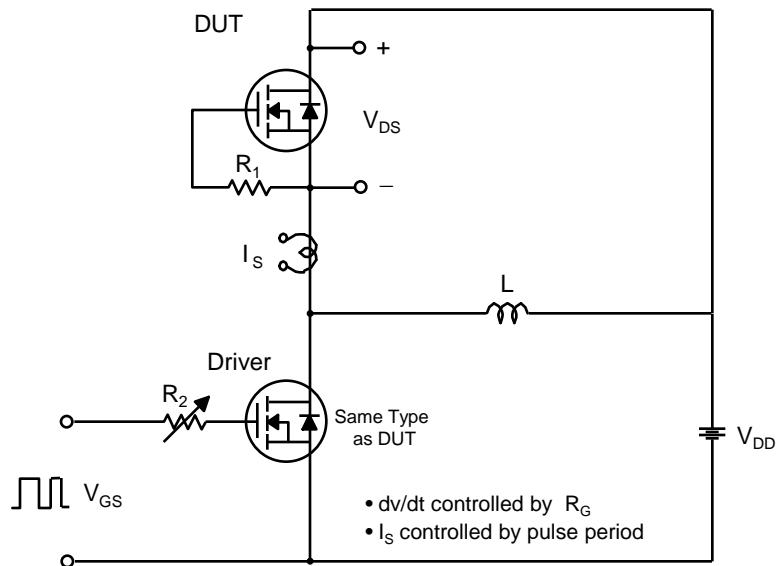


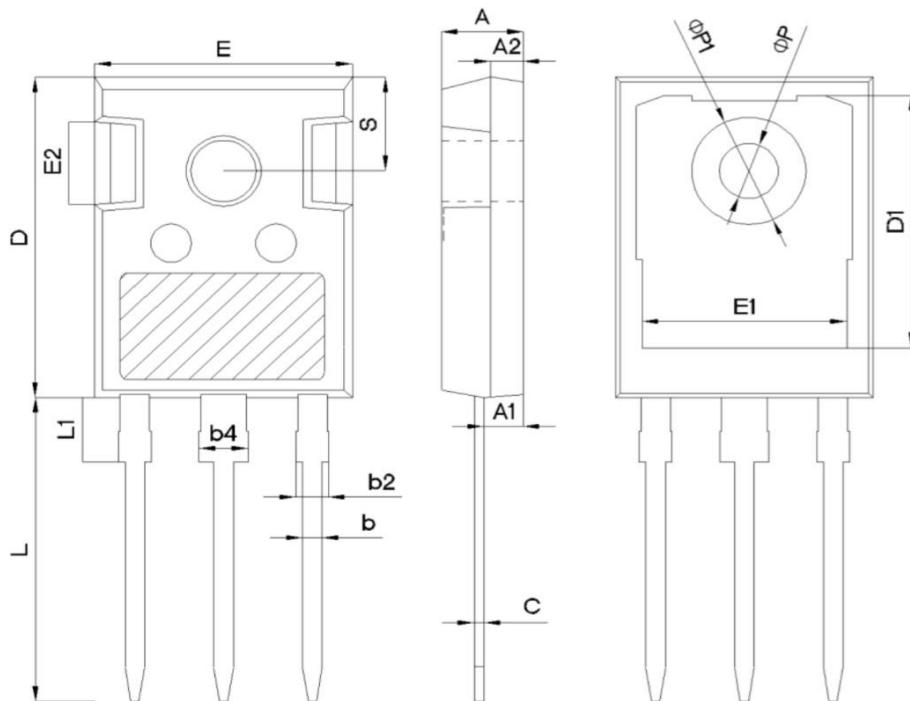
**Figure 10. Maximum Drain Current  
vs. Case Temperature**



**Figure 11. Transient Thermal Response Curve**

**Fig 12. Gate Charge Test Circuit & Waveform**

**Fig 13. Resistive Switching Test Circuit & Waveforms**

**Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms**


**Fig 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms**


**TO-247**


SYMBOL	mm		
	MIN	NOM	MAX
A	4.80	5.00	5.20
A1	2.21	2.41	2.61
A2	1.85	2.00	2.15
b	1.11	1.21	1.36
b2	1.91	2.01	2.21
b4	2.91	3.01	3.21
c	0.51	0.61	0.75
D	20.70	21.00	21.30
D1	16.25	16.55	16.85
E	15.50	15.80	16.10
E1	13.00	13.30	13.60
E2	4.80	5.00	5.20
E3	2.30	2.50	2.70
e	5.44B SC		
L	19.62	19.92	20.22
L1	-	-	4.30
$\Phi P$	3.40	3.60	3.80
$\Phi P1$	-	-	7.30
S	6.15B SC		